

RL78/G23

Handshake-based SPI Master Transmission/Reception

Introduction

This application note describes how the serial array unit (SAU) performs master transmission/reception by the simple SPI (CSI). The SAU uses the chip select ($\overline{CS}$) signal to select a slave device and perform single transmission/reception. The SAU also performs handshake processing using the BUSY signal.

Target Device

RL78/G23

When applying the sample program covered in this application note to another microcomputer, modify the program according to the specifications for the target microcomputer and conduct an extensive evaluation of the modified program.

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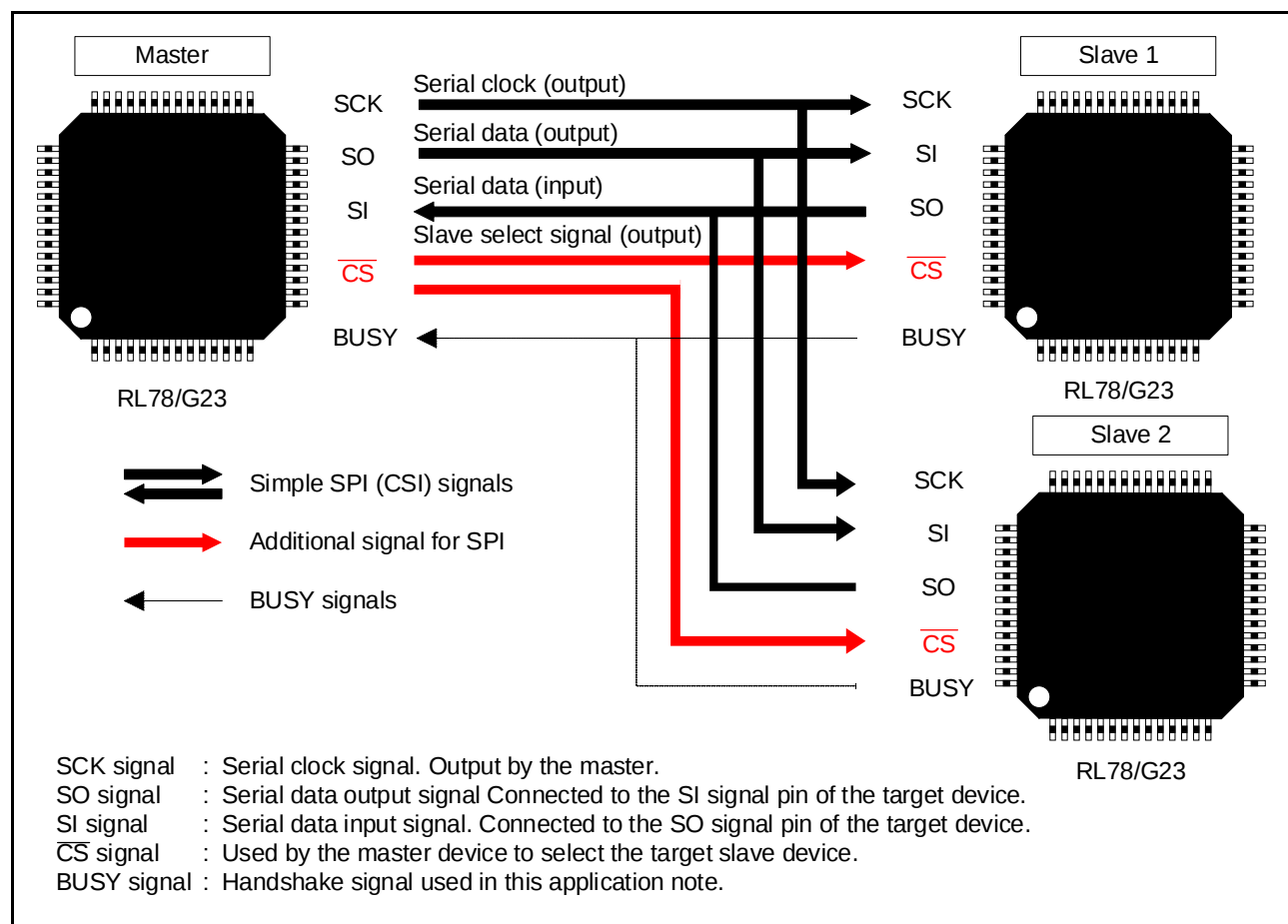
1. Specifications

The serial array unit (SAU) described in this application note performs CSI master transmission/reception. The chip select ($\overline{CS}$) signal uses the port. $\overline{CS}$ Handshake processing using the BUSY signal is also performed for the slave device selected by the $\overline{CS}$ signal.

1.1 Outline of CSI Communication

CSI communication is clock-synchronous serial communication using three signal lines, namely, serial clock (SCK), serial data input (SI), and serial data output (SO). SPI (Serial Peripheral Interface) uses an additional chip select ($\overline{CS}$) signal to select the slave device. The relationship among these signals is shown in Figure 1-1.

Figure 1-1 Outline of CSI Communication



The master first selects the slave with which it wants to communicate with the $\overline{CS}$ signal. Then, the master outputs data to the SCK signal line and the SO signal line in synchronization with the SCK signal, and inputs data from the SI signal line.

In SPI/CSI communication, the slave needs to become ready for communication by the time the master starts communication (sending the SCK signals). In this application note, the BUSY signal is used to confirm that the slave is ready for communication. The master detects a low-level BUSY signal and then initiates a communication session.

1.2 Outline of Communication

In this application note, a command and communication for the command are performed at intervals of 1 ms. A set of a command and communication for the command is defined as a slot. Figure 1-2 shows an outline of slot processing and Table 1-1 lists the commands to be used.

Figure 1-2 Outline of Slots

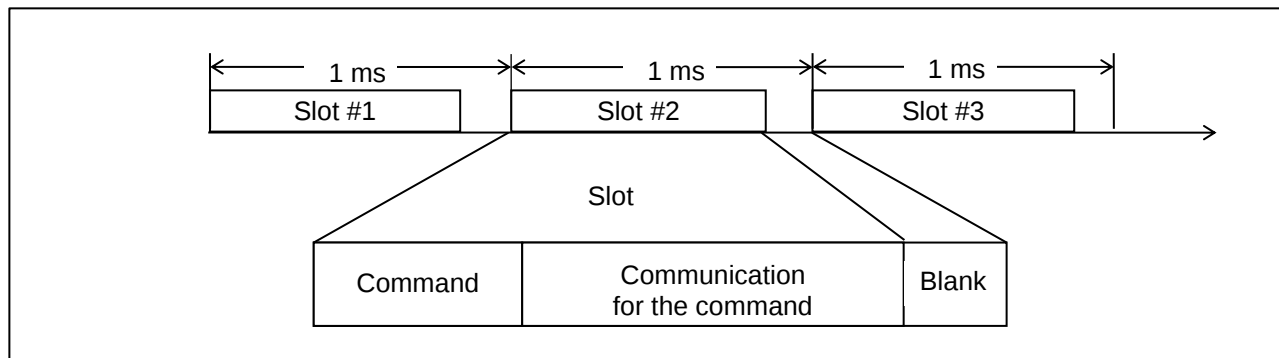


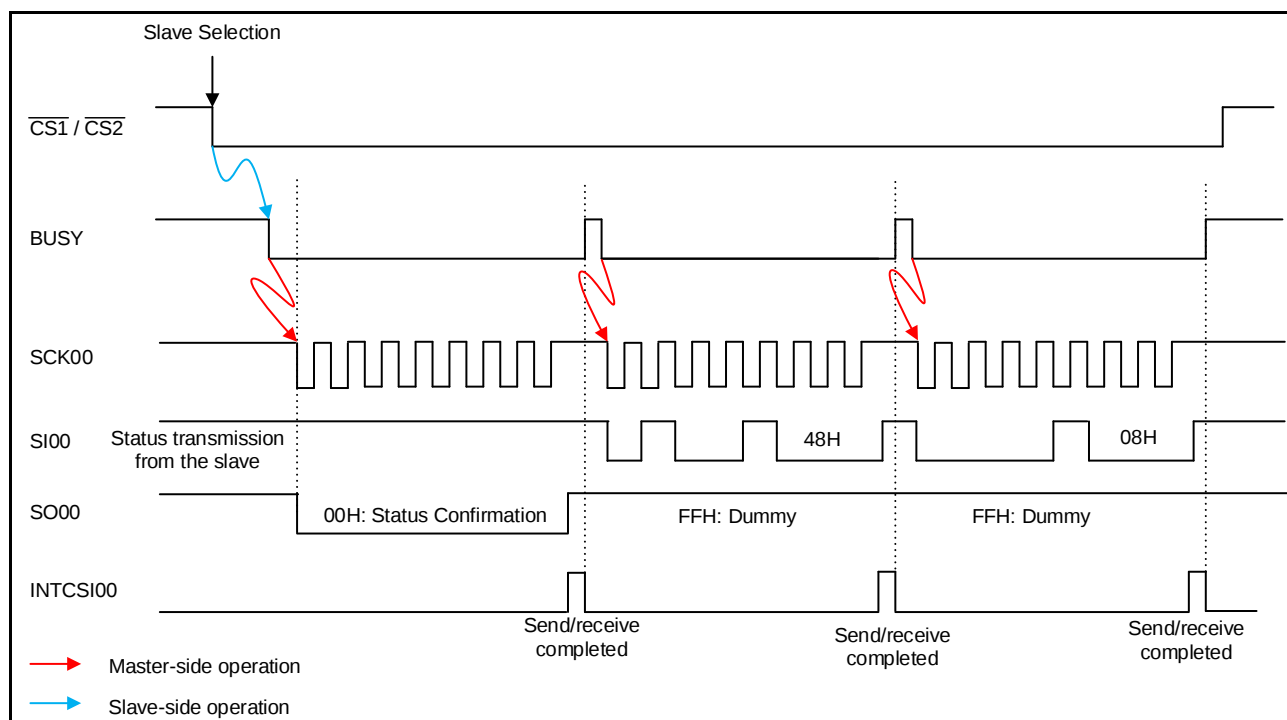
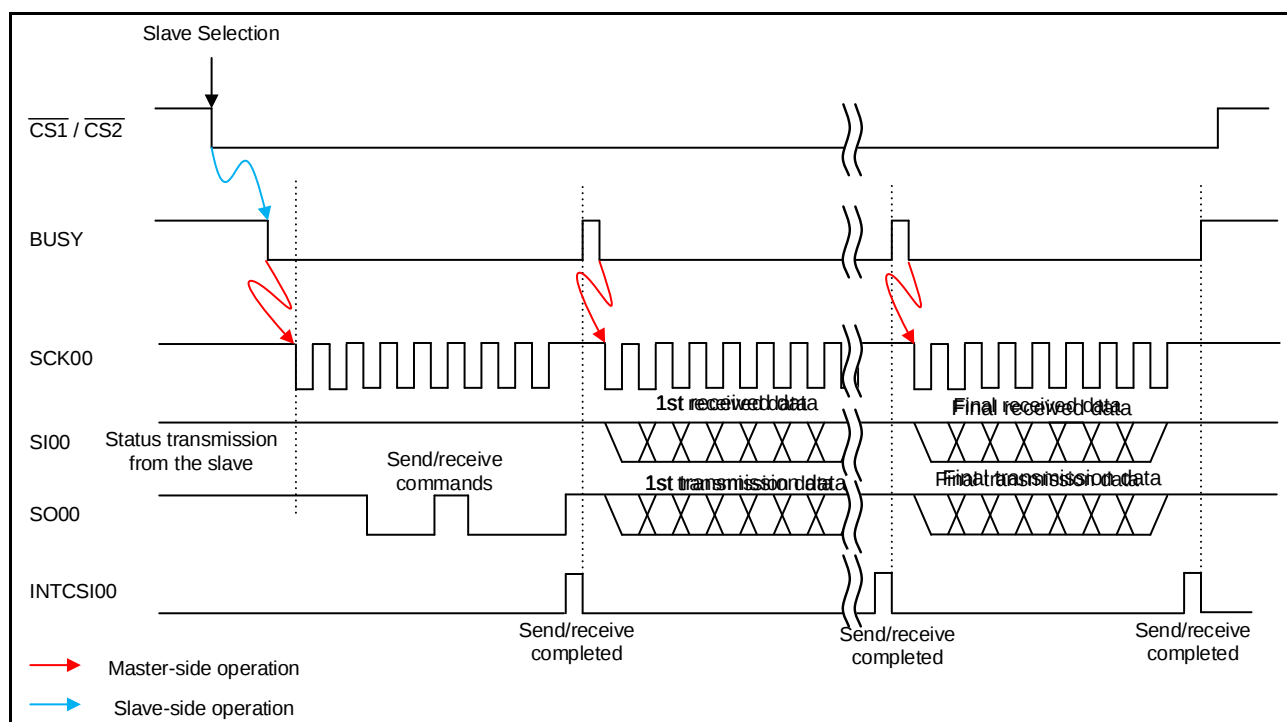
Table 1-1 Commands to be Used

Command	Outline of Operation
Status check	Checks the number of data characters that the slave can transmit or receive.
Receive	Receives data from the slave.
Transmit	Transmits data to the slave.
Transmit/receive	Transmits and receives data to and from the slave.

Table 1-2 lists the peripheral functions and their uses. Figure 1-3 and Figure 1-4 show the CSI communication operations.

Table 1-2 Peripheral Functions and Their Uses

Peripheral Function	Use
Serial array unit 0	Performs CSI master communication using the SCK00 signal (clock output), SI00 signal (receive data), and SO00 signal (transmit data).
Port	Uses P52 for $\overline{\text{CS1}}$ signal, P53 for $\overline{\text{CS2}}$ signal, and P54 for BUSY signal.
Timer array unit 0 Channel 3	The upper 8 bits are used as a 1-ms interval timer. The lower 8 bits are used as a 16- μ s interval timer.

Figure 1-3 Timing chart for status check commands**Figure 1-4 Timing chart of commands sent and received**

1.3 Communication Format

Table 1-3 lists the characteristics of the CSI communication format that is used in the sample code.

Table 1-3 Communication Format

Item	Specification	Remarks
Communication speed	1 Mbps	About 200 kbps at minimum
Data bit length	8 bits/character	
Transfer order	MSB first	
Communication type	Type 1	
Communication mode	Single transfer	
Communication direction	Receive/transmit/transmit and receive	
Maximum number of characters transferred	63 characters/slot	8 characters by default

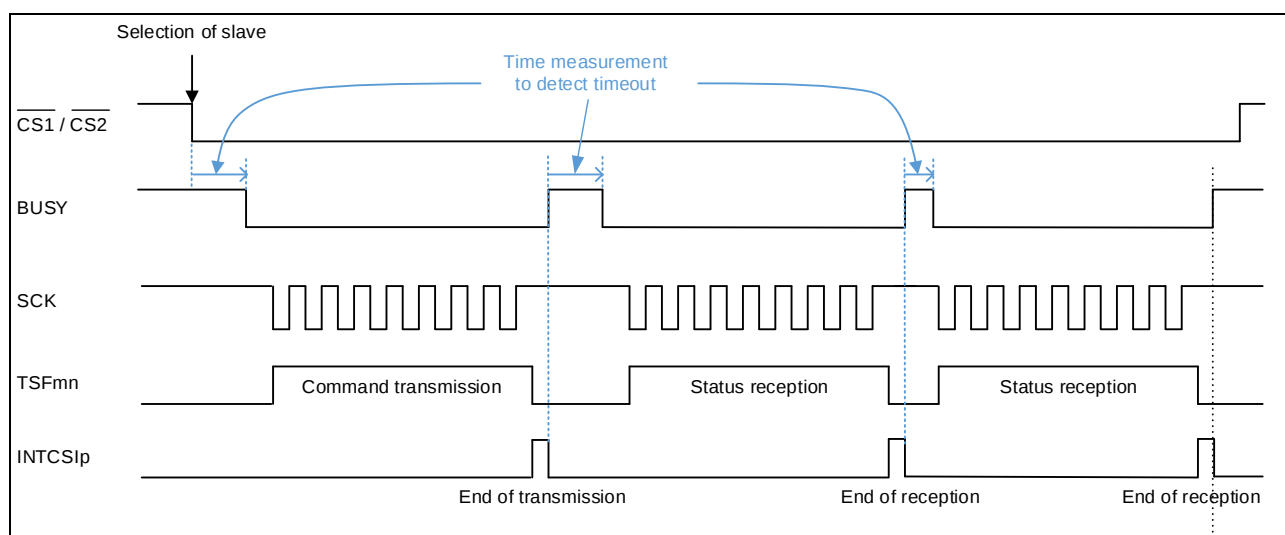
1.4 Handshake

In this application note, handshaking using the BUSY signal is performed to secure the setup time required for the communication operation on the slave side. A timeout of 16 μ s is set up in case no response using the BUSY signal is returned from the slave. If no response is returned from the slave within this period, the master assumes that the slave cannot establish a communication (or does not exist) and terminates communication processing.

Figure 1-5 shows an example of handshaking for status checking. The master measures the time from the falling edge of the $\overline{CS}$ signal until the BUSY signal goes low. When detecting that the BUSY signal goes low without the timeout, the master sends the command. After confirming that command transmission is completed through the transfer completion interrupt, the master measures the time until the BUSY signal goes low again. In this way, the master synchronizes with the slave by checking the BUSY signal each time communication starts.

However, if the slave supports continuous reception or can secure enough time to prepare communication data, synchronization using the BUSY signal is not necessary.

Figure 1-5 Handshaking Example



Generally, the BUSY signal is not required for SPI communication-dedicated slave devices such as EEPROM because they are always ready for communication. When connecting such SPI communication-dedicated slave devices, pull down the BUSY signal input pin. Additionally, the timeout processing can be removed by deleting the wait() function from the program. In such a case, perform communication according to the commands that are defined for the SPI communication-dedicated slave devices and their communication protocol.

1.5 Specification Details

After completion of initialization, this sample code selects a slave, checks that slave's status, and then transmits and receives data, switches slaves, and repeats the same operation.

(1) Initialize the port.

<Conditions for setting the port>

- Use P52 controlling the $\overline{\text{CS1}}$ signal as an output port to output a high-level signal.
- Use P53 controlling the $\overline{\text{CS2}}$ signal as an output port to output a high-level signal.
- Use P54 detecting the BUSY signal as an input port.

(2) Initialize the timer.

<Conditions for setting the timer>

- Run Channel 3 as two 8-bit interval timers.
- Set the operating clock frequency to 125 kHz (derived by dividing fCLK by 256).
- Use the upper TM03H as a 1-ms interval timer.
- Use the lower TM03 as a 16- μ s interval timer.
- Set the priority of the interrupts (INTTM03H, INTTM03) to the lowest level (3, by default).

(3) Initialize the CSI.

<Conditions for setting the CSI>

- Use SAU0 channel 0 as CSI00.
- Use CK00 as the transfer clock.
- Assign the clock output to the P10/SCK00 pin, the data input to the P11/SI00 pin, and the data output to the P12/SO00 pin.
- Use single transfer mode as the transfer mode.
- Set the data length to 8 bits.
- Set the phase between the data and clock to type 1.
- Set the order of data transfer mode to MSB first.
- Set the transfer rate to 1 Mbps.
- Use transmission end and reception end interrupts as the interrupt (INTCSI00).
- Set the priority of the interrupt (INTCSI00) to the lowest level (3, by default).

(4) After initialization is completed, the master performs communication with the slave as shown in the following steps.

- ① The master waits in HALT mode for a 1-ms interval timer interrupt (INTTM03H).
- ② When the master is released from HALT mode by an INTTM03 interrupt, it issues the $\overline{CS}$ signal to select the slave that is specified in the g_slave_select_flag flag, and then waits for a response from the slave.
- ③ When the BUSY signal goes low, the master proceeds to step 4. When a timeout is detected, the master deselects the slave and proceeds to step 9.
- ④ The master transmits a status check command and receives the slave status. When a timeout is detected, or the slave status cannot be received, the master deselects the slave and proceeds to step 9. When the slave status is received, the master deselects the $\overline{CS}$ signal.
- ⑤ The master again waits in HALT mode for a 1-ms interval timer interrupt (INTTM03H).
- ⑥ When the master is released from HALT mode by an INTTM03 interrupt again, it issues the $\overline{CS}$ signal to select the slave that is specified in the g_slave_select_flag flag, and then waits for a response from the slave.
- ⑦ When the master detects that the BUSY signal goes low, it proceeds to step 8. When a timeout is detected, the master deselects the slave and proceeds to step 9.
- ⑧ The master transmits and receives the number of data characters according to the status checked in step 4. When a timeout is detected, the master deselects the slave.
- ⑨ The master changes the g_slave_select_flag flag to switch the target slave. These steps are subsequently repeated from step 1.

(5) Commands

Each communication operation begins with the transmission of a 1-byte command. Table 1-4 lists the command formats. The master transmits a status check command and receives the response from the slave in the first slot of a communication sequence. The master confirms that the number of data characters that the target slave can transmit or receive is equal to or greater than the specified number of data characters to be transmitted or received. Then, the master transmits/receives data for the specified number of data characters to/from the slave.

Table 1-4 Command Formats

Command Code		Command Outline
Status check	00000000B	Checks the number of data characters that the slave can transmit or receive. The following responses can be made by the slave: 01xxxxxxB: The number of characters that the slave can transmit is xxxxxxB. 00xxxxxxB: The number of characters that the slave can receive is xxxxxxB.
Reception	01xxxxxxB	The master receives xxxxxxB bytes of data.
Transmission	10xxxxxxB	The master transmits xxxxxxB bytes of data.
Transmission/reception	11xxxxxxB	The master transmits and receives xxxxxxB bytes of data.

(6) Switching communication commands

Receive, transmit, and transmit/receive commands can be switched by changing the comment-out lines in the main.c file. The transmit/receive command is set by default.

```
/*-----  
Send Receive command  
-----*/  
  
CSI00_Send_Receive();           /*call Send Receive function*/  
/* CSI00_Send(); */  
/* CSI00_Receive(); */  
g_slave_select_flag ^= 1U;     /*change slave number*/  
g_status_confirmation_flag = 0; /* clear g_status_confirmation_flag */
```

2. Operation Confirmation Conditions

The operation of the sample code provided with this application note has been tested under the following conditions.

Figure 2-1 Operation Confirmation Conditions

Item Description	Item Description
MCU used	RL78/G23 (R7F100GLG)
Board used	RL78/G23 Fast Prototyping Board (RTK7RLG230CLG000BJ)
Operating frequency	- High-speed on-chip oscillator clock (fIH): 32 MHz - CPU/peripheral hardware clock: 32 MHz
Operating voltage	During VDD operation: 5.0 V (4.0V~5.5V) LVD0 detection voltage: Reset mode At rising edge TYP. 1.90 V (1.84 V to 1.95 V) At falling edge TYP. 1.86 V (1.80 V to 1.91 V)
Integrated development environment (CS+)	CS+ V8.10.00 from Renesas Electronics Corp.
C compiler (CS+)	CC-RL V1.12.01 from Renesas Electronics Corp
Integrated development environment (e2studio)	e2 studio V2023-10 (23.10.0) from Renesas Electronics Corp.
C compiler (e2studio)	CC-RL V1.12.01 from Renesas Electronics Corp.
Integrated development environment (IAR)	IAR Embedded Workbench for Renesas RL78 V5.10.1 from IAR Systems Corp.
C compiler (IAR)	IAR C/C++ Compiler for Renesas RL78 V5.10.1 from IAR Systems Corp.
Smart Configurator	V1.8.0 from Renesas Electronics Corp.
Board Support Package (r_bsp)	V1.30 from Renesas Electronics Corp.

3. Related Application Notes

See also the following application notes, which are related to this application note:

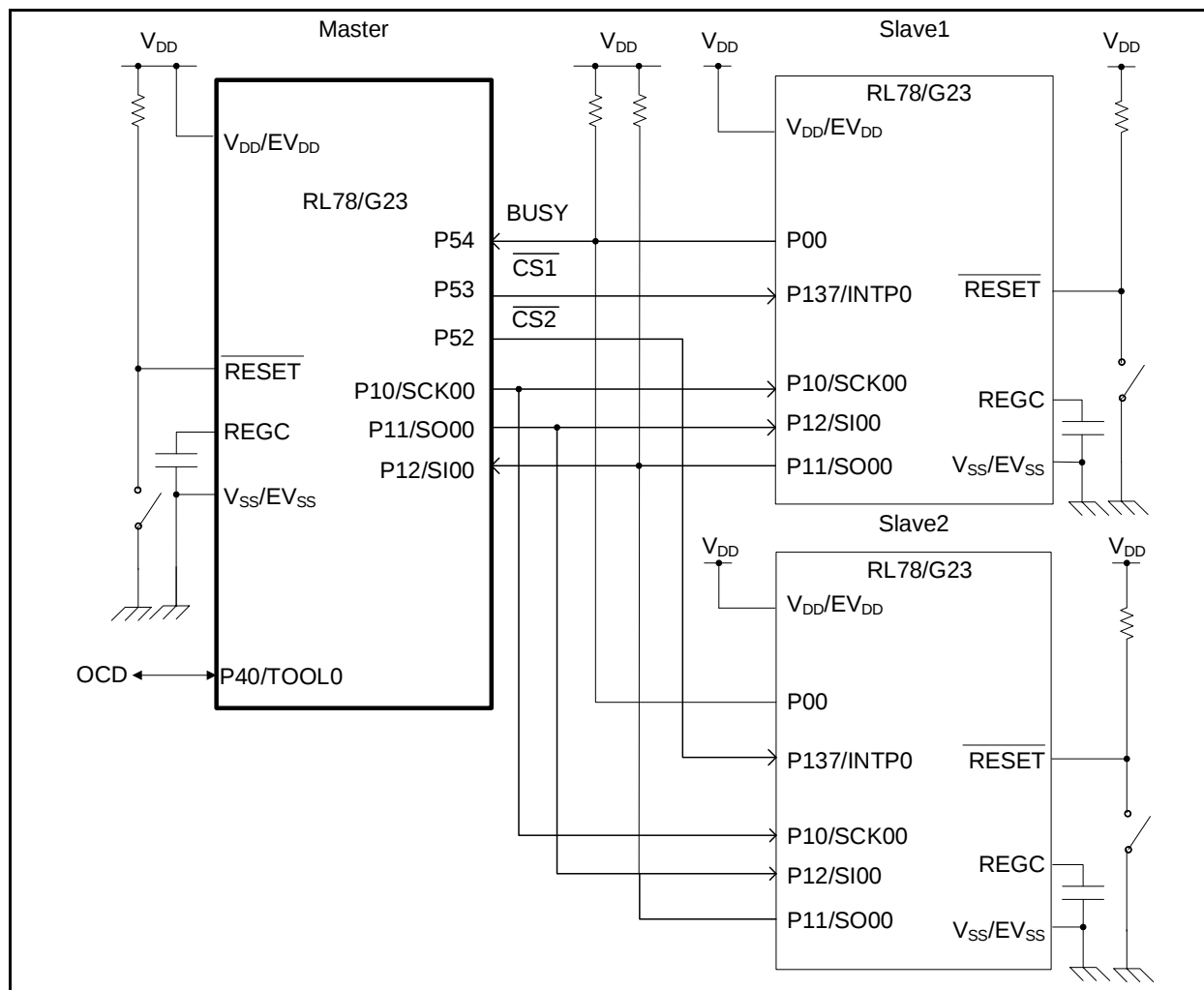
RL78/G23 Handshake-based SPI Slave Transmission/Reception (R01AN5890J) APPLICATION NOTE

4. Hardware Descriptions

4.1 Example of Hardware Configuration

Figure 4-1 shows an example of the hardware configuration used in the application note.

Figure 4-1 Hardware Configuration



Note 1. This schematic circuit diagram is simplified to show the outline of connections. When creating circuits, design them so that they meet electrical characteristics by properly performing pin processing. (Connect input-only ports to V_{DD} or V_{SS} individually through a resistor.)

Note 2. Connect pins (with a name beginning with EV_{SS}), if any, to V_{SS}, and connect pins (with a name beginning with EV_{DD}), if any, to V_{DD}.

4.2 List of Pins to be Used

Table 4-1 lists the pins to be used and their functions

Table 4-1 Pins to be Used and Their Functions

Pin Name	I/O	Description
P10/EI10/EO10/SCK00/SCL00/(TI07)/(TO07)	Output	Serial clock output pin
P11/EI11/EO11/SI00/RxD0/TOOLRxD/SDA00/(TI06)/(TO06)	Input	Data reception pin
P12/EI12/EO12/SO00/TxD0/TOOLTxD/(INTP5)/(TI05)/(TO05)	Output	Data transmission pin
P54	Input	BUSY signal input from slaves
P53/(INTP11)	Output	Slave 2 select signal
P52/(INTP10)	Output	Slave 1 select signal

Caution In this application note, only the used pins are processed. When actually designing your circuit, make sure the design includes sufficient pin processing and meets electrical characteristic requirements.

5. Description of the Software

5.1 List of Option Byte Settings

Table 5-1 summarizes the settings of the option bytes.

Table 5-1 Option Byte Settings

Address	Setting Value	Description
000C0H	1110 1111B (EFH)	Stops the watchdog timer operation. (Stops counting after the release of the reset state.)
000C1H	1111 1110B (FEH)	LVD reset mode Detection Voltage: On the rising edge: TYP. 1.90V (1.84 V to 1.95 V) On the falling edge: TYP. 1.86V (1.80 V to 1.91 V)
000C2H	11101000B (E8H)	HS mode, HOCO: 32 MHz
000C3H	10000100B (84H)	Enables the on-chip debugging function.

5.2 List of Constants

Table 5-2 lists the constants that are used in the sample code.

Table 5-2 Constants Used in the Sample Code

Constant Name	Definition location	Setting Value	Description
CS1_pin	r_cg_userdefine.h	P5_bit.no2	Port register to control the $\overline{CS1}$ signal
CS2_pin	r_cg_userdefine.h	P5_bit.no3	Port register to control the $\overline{CS2}$ signal
BUSYIN	r_cg_userdefine.h	P5_bit.no4	Port register to detect the BUSY signal
TX_NUM	main.c	32	Number of data characters to be transmitted
RX_NUM	main.c	32	Number of data characters to be received
TX_RX_NUM	main.c	32	Number of data characters to be transmitted/received
data_length	main.c	1	Data length
MODE[]	main.c	*1	Command format
TX_DATA[]	main.c	*2	Stores 63 characters of transmit data, the maximum number of characters transferred.

Notes: 1. For details, see Table 1-4.

2. In this application note, ASCII codes from 0x20 to 0x5F are stored.

5.3 List of Variables

Table 5-3 lists the global variables that are used in this sample code.

Table 5-3 Global Variables Used in the Sample Code

Type	Variable Name	Contents	Function Used
uint8_t	g_tx_data	Buffer for transmit data	main.c
uint8_t	g_rx_data	Buffer for receive data	main.c
uint8_t	g_slave_select_flag	Slave select flag	main.c
uint8_t	g_status_confirmation_flag	Status check flag	main.c
uint8_t	g_timeout_flag	Timeout flag	main.c
uint8_t	g_num	Number of data characters that the slave can transmit	main.c
uint8_t	g_rx_data_stored[]	Stores receive data.	main.c

5.4 List of Functions

Table 5-4 lists the functions that are used in the sample code.

Table 5-4 Functions

Function Name	Outline	Source file
main	Main processing	main.c
CSI00_Status_check	CSI status check	main.c
CSI00_Send_Receive	CSI transmission/reception	main.c
CSI00_Send	CSI transmission	main.c
CSI00_Receive	CSI reception	main.c
wait	Wait for slave response	main.c

5.5 Function Specifications

This section describes the specifications for the functions that are used in the sample code.

[Function Name] main

Synopsis	Main processing
Header	r_smc_entry.h
Declaration	void main(void)
Explanation	Starts the operation of CSI00 and TAU03H. Selects a slave. Switches the slave select flag, g_slave_select_flag. When slave 1 is selected: g_slave_select_flag = 0 When slave 2 is selected: g_slave_select_flag = 1 Sets the status check flag, g_status_confirmation_flag, to 0 (initial value) after detection of a timeout or completion of transmission/reception.
Arguments	None
Return value	None
Remarks	None

[Function Name] CSI00_Status_check

Synopsis	CSI status check
Header	r_smc_entry.h
Declaration	void CSI00_Status_check (void)
Explanation	Checks the status of the slave. Sets the status check flag, g_status_confirmation_flag, to 1 when the slave status check ends normally.
Arguments	None
Return value	None
Remarks	None

[Function Name] CSI00_Send_Receive

Synopsis	CSI transmission/reception
Header	r_smc_entry.h
Declaration	void CSI00_Send_Receive (void)
Explanation	Performs the master transmission/reception processing.
Arguments	• None
Return value	• None
Remarks	None

[Function Name] CSI00_Send

Synopsis	CSI transmission
Header	r_smc_entry.h
Declaration	void CSI00_Send (void)
Explanation	Performs the master transmission processing.
Arguments	• None
Return value	• None
Remarks	None

[Function Name] CSI00_Receive

Synopsis	CSI reception
Header	r_smc_entry.h
Declaration	void CSI00_Receive (void)
Explanation	Performs the master reception processing.
Arguments	• None
Return value	• None
Remarks	None

[Function Name] wait

Synopsis	Wait for slave response
Header	r_smc_entry.h
Declaration	uint8_t wait(void)
Explanation	Waits until the BUSY signal goes low.
Arguments	• None
Return value	0: Detects that the BUSY signal goes low. 1: Detects a timeout.
Remarks	None

5.6 Flowcharts

5.6.1 Flowchart of Main Processing

Figure 5-1 to Figure 5-2 show the overall flow of processing in this application note.

Figure 5-1 Main Processing 1/2

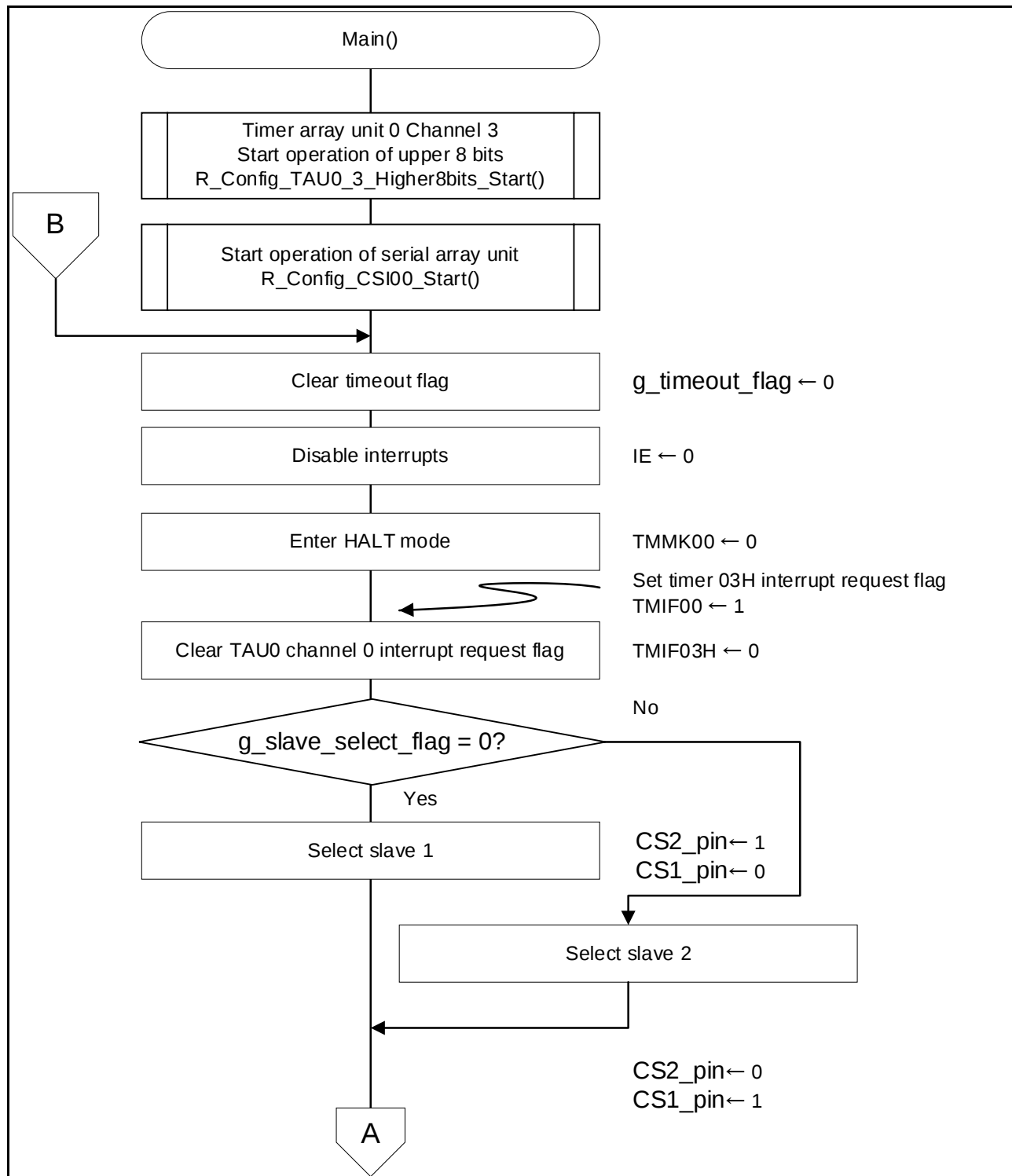
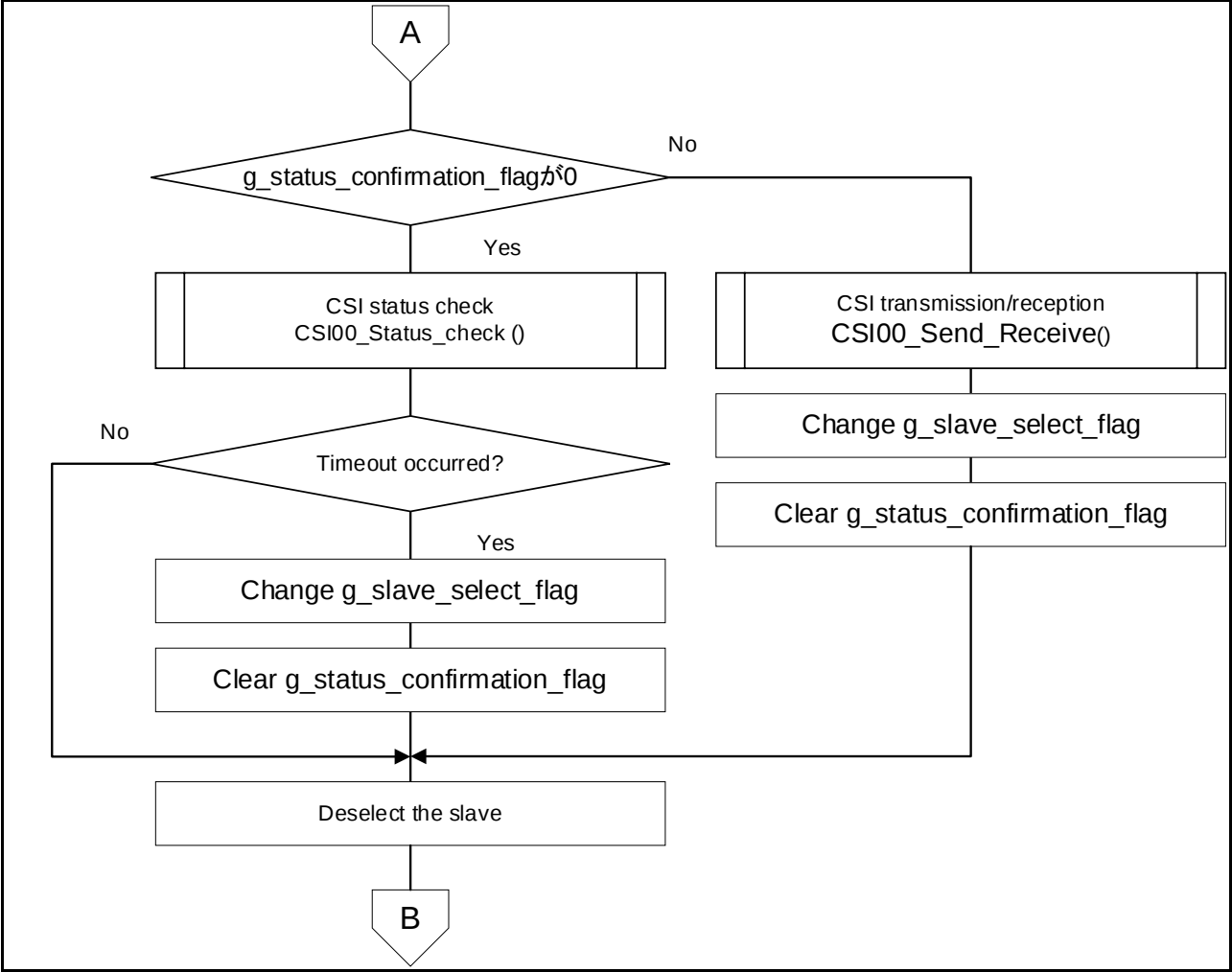


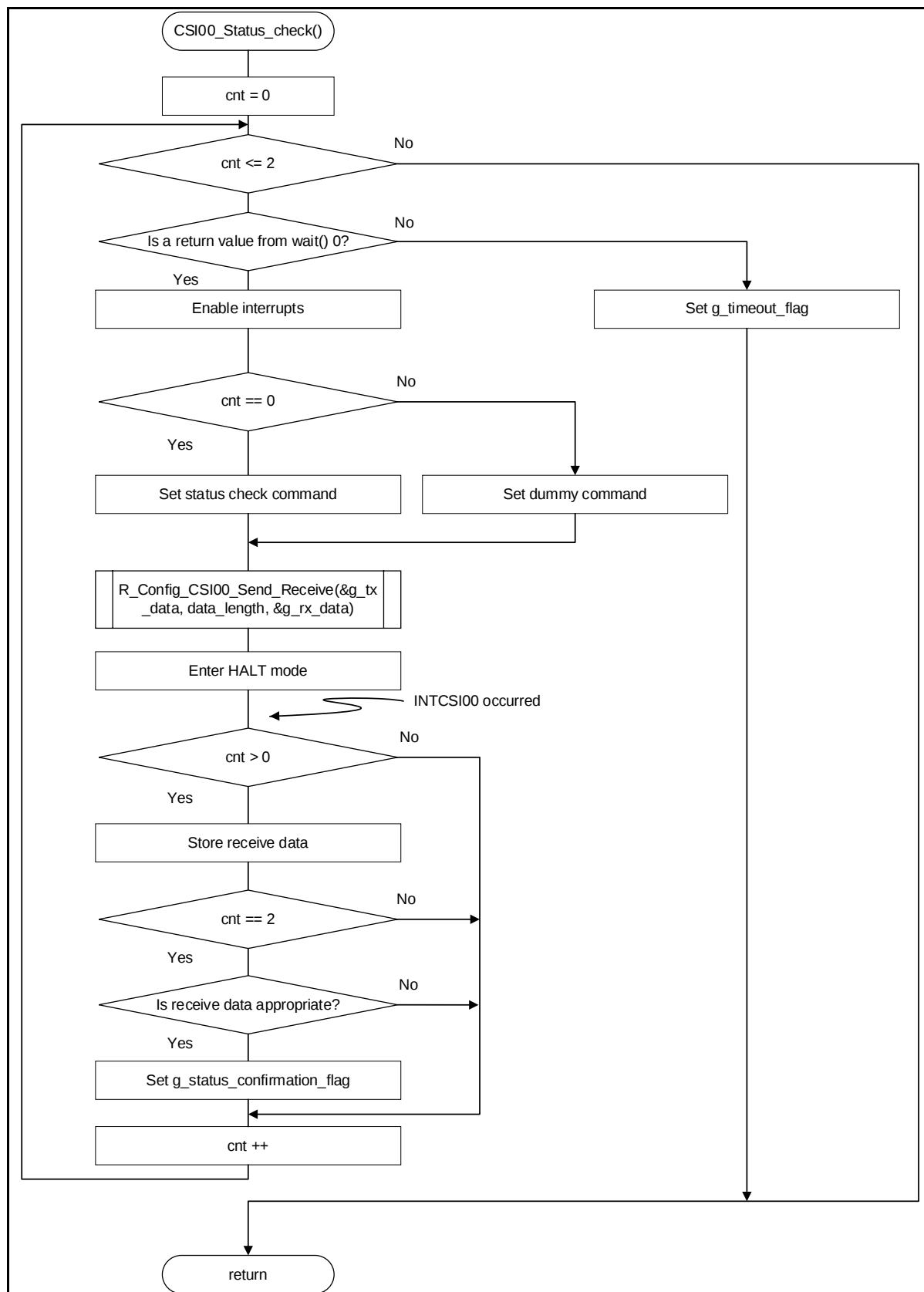
Figure 5-2 Main Processing 2/2



5.6.2 Flowchart of CSI Status Check

Figure 5-3 shows the flow of status checking.

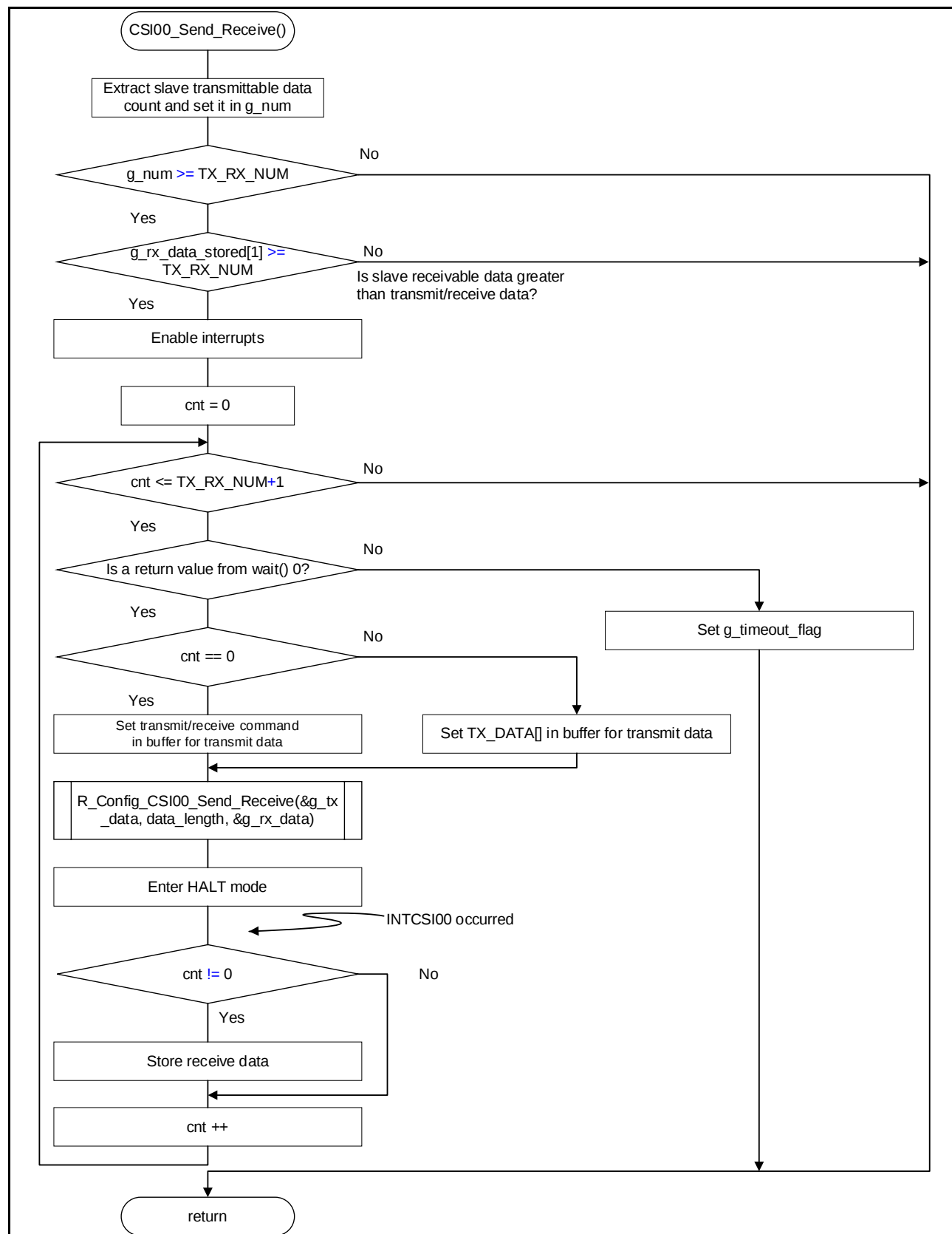
Figure 5-3 CSI Status Check



5.6.3 Flowchart of CSI Transmission/Reception

Figure 5-4 shows the flow of transmission and reception.

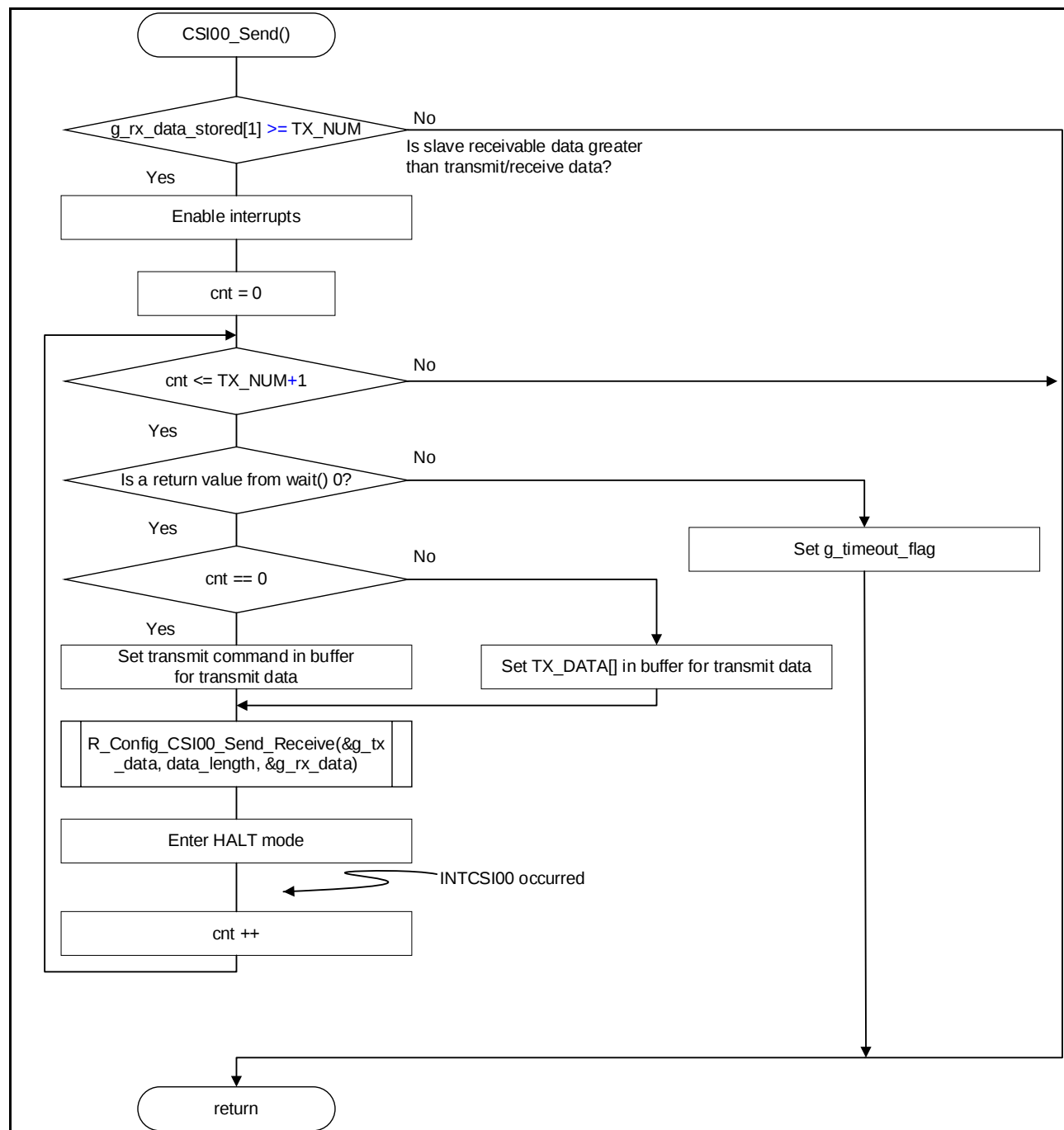
Figure 5-4 CSI Transmission/Reception



5.6.4 Flowchart of CSI Transmission

Figure 5-5 shows the flow of transmission.

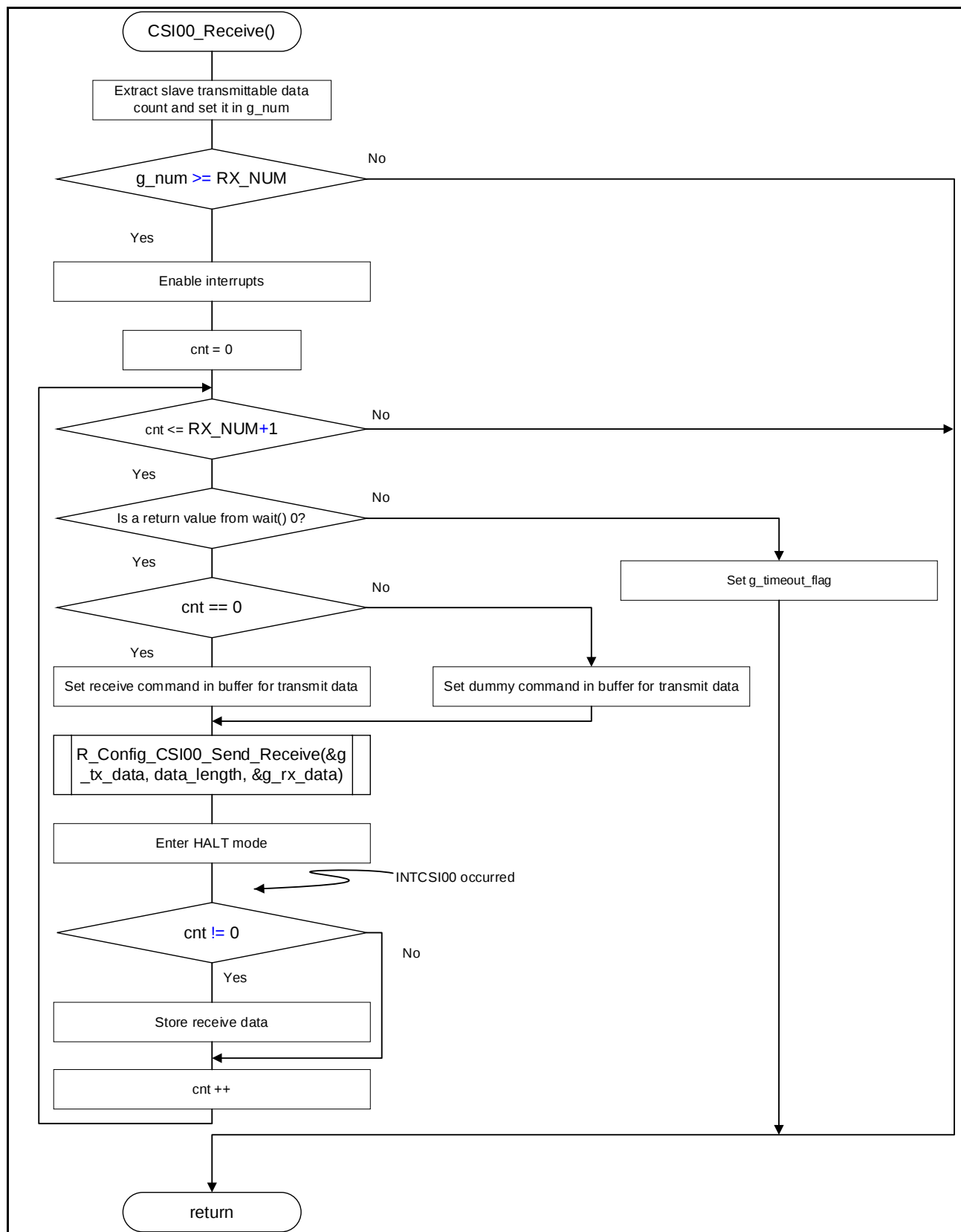
Figure 5-5 CSI Transmission



5.6.5 Flowchart of CSI Reception

Figure 5-6 shows the flow of reception.

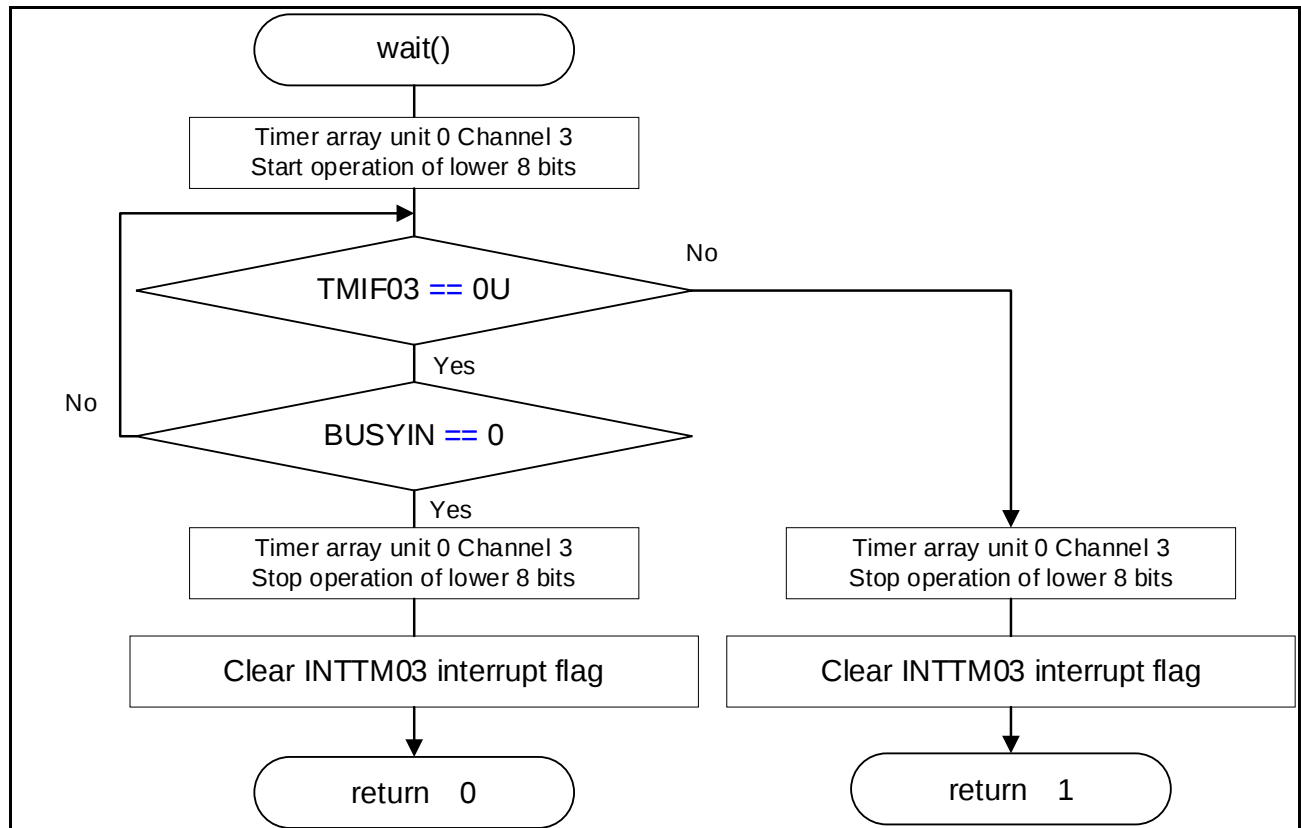
Figure 5-6 CSI Reception



5.6.6 Flowchart of Wait for Slave Response

Figure 5-7 shows the flow of wait for slave response.

Figure 5-7 Wait for Slave Response



6. Sample Code

Sample code can be downloaded from the Renesas Electronics website.

7. Reference Documents

RL78/G23 User's Manual: Hardware (R01UH0896)

RL78 family user's manual software (R01US0015)

The latest versions can be downloaded from the Renesas Electronics website.

Technical update

The latest versions can be downloaded from the Renesas Electronics website.

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Revision History

Rev.	Date	Description	
		Page	Summary
1.00	2022.12.16	-	First Edition
1.01	2023.12.1	10	Updated the Operation Confirmation Conditions
		11	Figure 4-1: Reset Circuit Modification

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

6. Voltage application waveform at input pin

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).

7. Prohibition of access to reserved addresses

Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.

8. Differences between products

Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

Notice

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5. You shall not alter, modify, copy, or reverse engineer any Renesas Electronics product, whether in whole or in part. Renesas Electronics disclaims any and all liability for any losses or damages incurred by you or third parties arising from such alteration, modification, copying or reverse engineering.
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(Rev.5.0-1 October 2020)

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